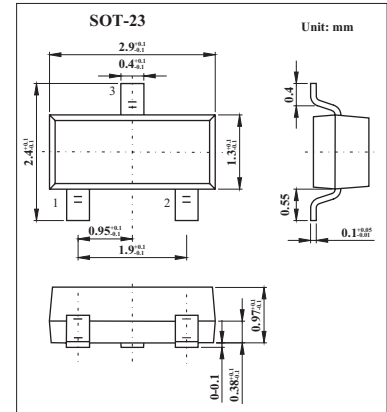


350mW Surface Mount Zener Diodes

BZX84C30

■ Features

- Planar Die Construction
- 350mW Power Dissipation
- Ideally Suited for Automated Assembly Processes



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Forward Voltage at If = 10 mA	V _F	0.9	V
Power Dissipation *	P _D	350	mW
Junction Temperature	T _j	150	°C
Storage Temperature Range	T _s	-65 to + 150	°C
Thermal Resistance Junction to Ambient Air *	R _{thA}	417	°C/W

*Device mounted on FR-4 PC board with recommended pad layout,

■ Electrical Characteristics Ta = 25°C (unless otherwise noted)

Type Number	Zener Voltage Range *1			Maximum Zener Impedance *2			Maximum Reverse Current *1		Typical Temperature Coefficient @ I _{ZT} mV/°C		
	V _Z @ I _{ZT}			Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}		I _R	V _R	Min	Max	
	Nom (V)	Min (V)	Max (V)	mA	Ω	Ω	mA	μA	V		
BZX84C30	30	28.0	32.0	2.0	80	300	0.5	0.1	21	24.4	29.4

*1. Short duration test pulse used to minimize self-heating effect.

*2. f = 1KHz.

■ Marking

Marking	Y11
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BZX84C30

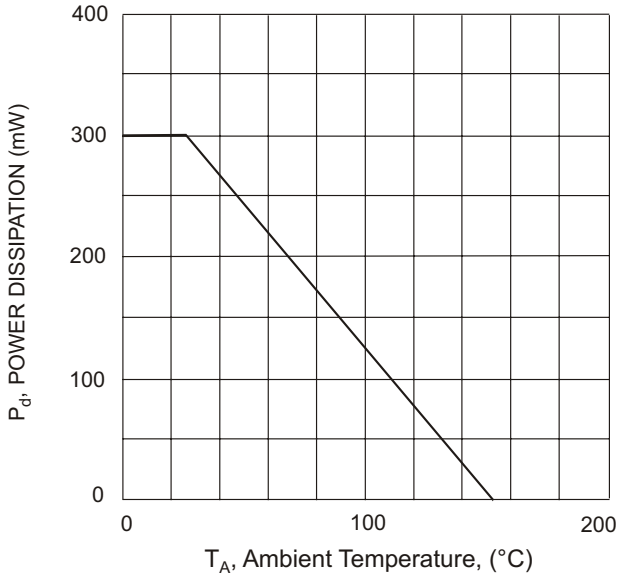


Fig. 1 Power Derating Curve

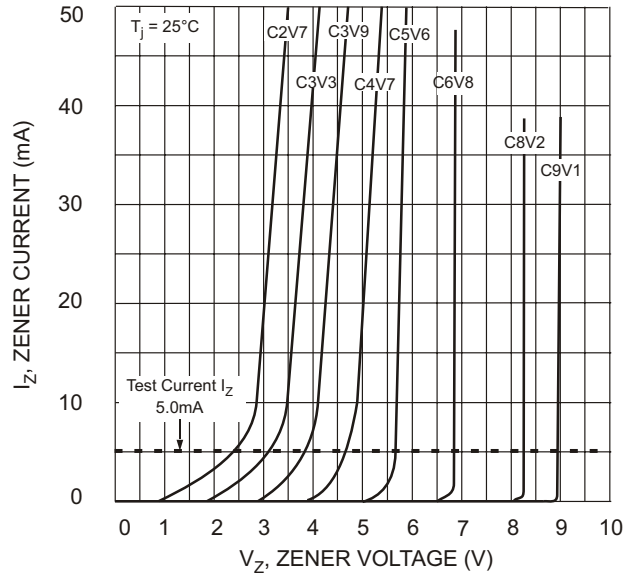


Fig. 2 Zener Breakdown Characteristics

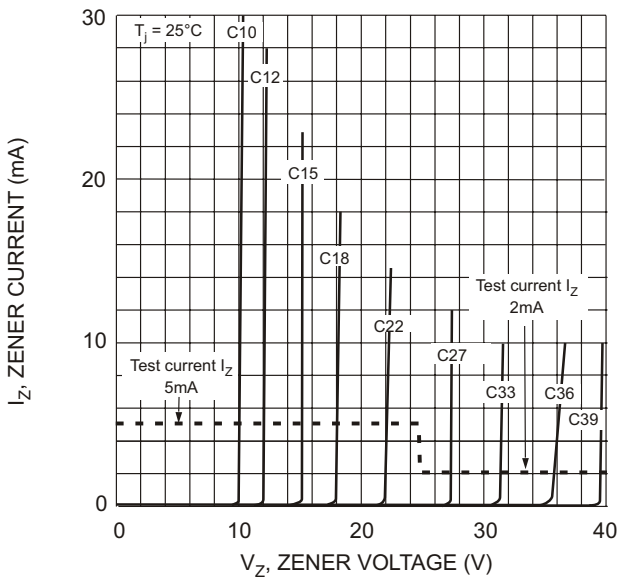


Fig. 3 Zener Breakdown Characteristics

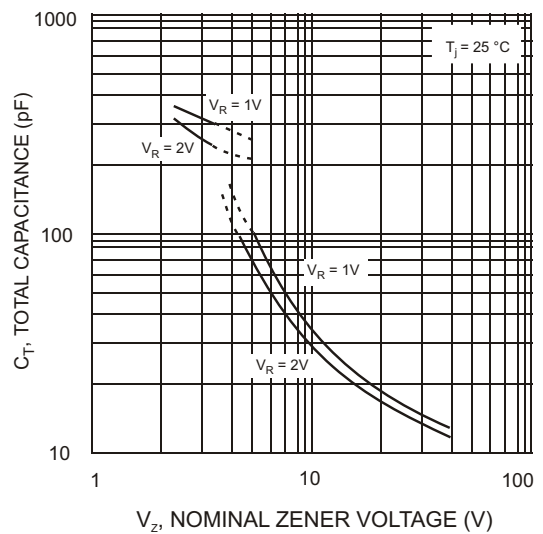


Fig. 4 Total Capacitance vs Nominal Zener Voltage